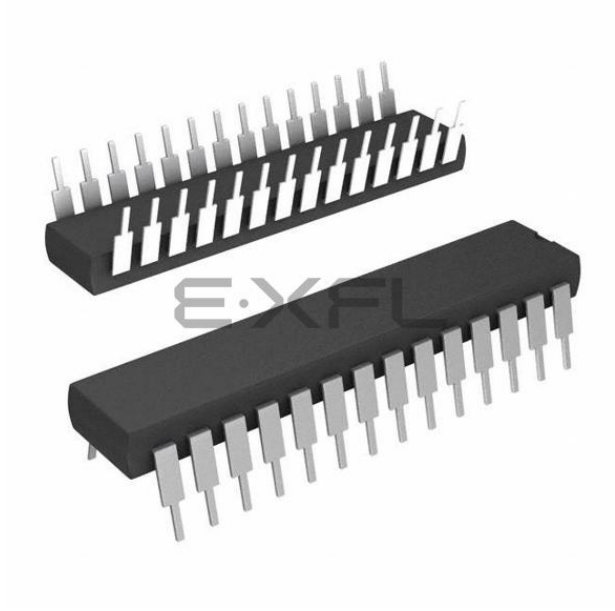


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

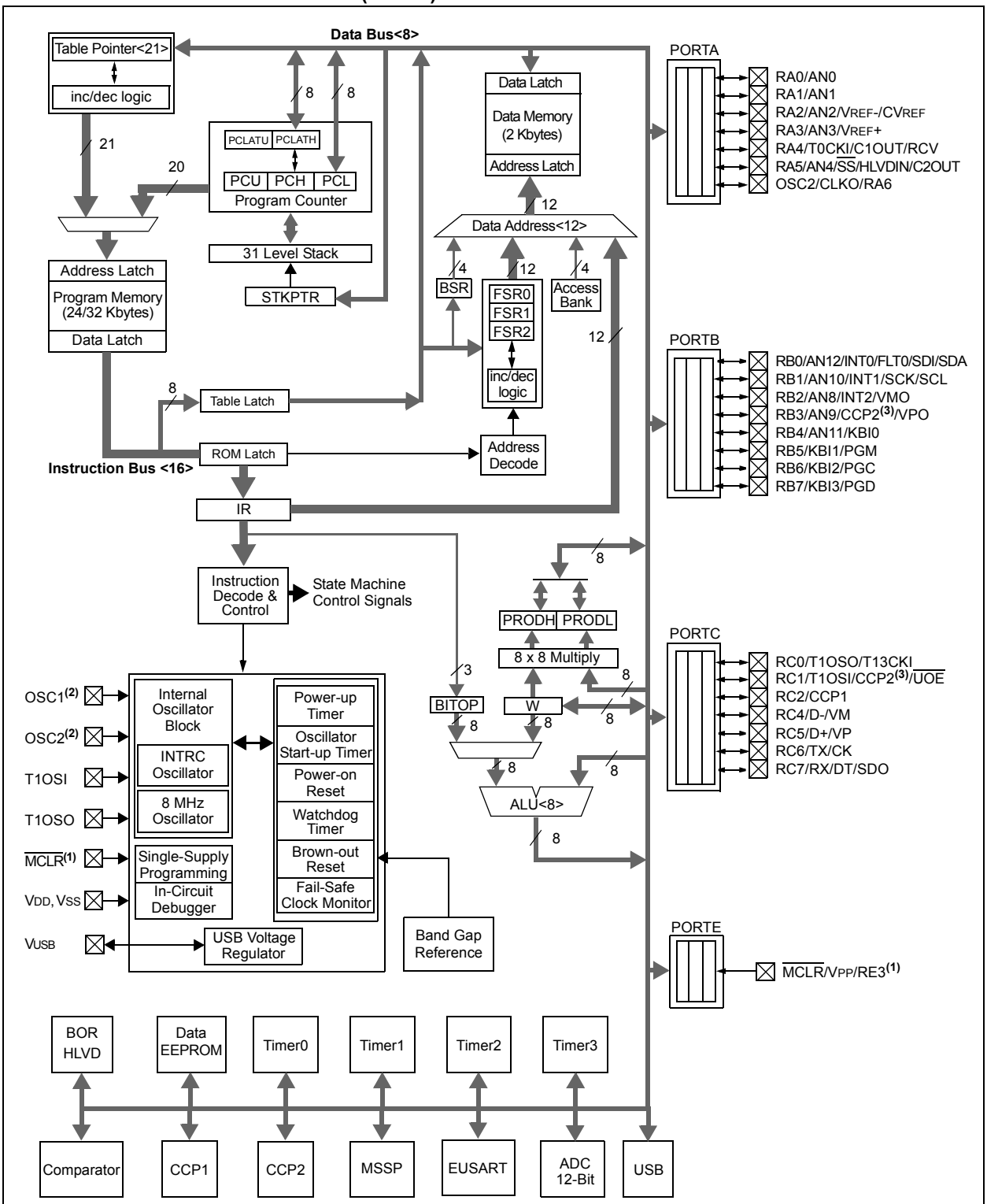
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	48MHz
Connectivity	I²C, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	24KB (12K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f2458-i-sp

TABLE 1-1: DEVICE FEATURES

Features	PIC18F2458	PIC18F2553	PIC18F4458	PIC18F4553
Operating Frequency	DC – 48 MHz	DC – 48 MHz	DC – 48 MHz	DC – 48 MHz
Program Memory (Bytes)	24576	32768	24576	32768
Program Memory (Instructions)	12288	16384	12288	16384
Data Memory (Bytes)	2048	2048	2048	2048
Data EEPROM Memory (Bytes)	256	256	256	256
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Timers	4	4	4	4
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/ Compare/PWM Modules	0	0	1	1
Serial Communications	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART	MSSP, Enhanced USART
Universal Serial Bus (USB) Module	1	1	1	1
Streaming Parallel Port (SPP)	No	No	Yes	Yes
12-Bit Analog-to-Digital Converter Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Comparators	2	2	2	2
Resets (and Delays)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)	POR, BOR, WDT, RESET Instruction, Stack Full, Stack Underflow, MCLR (optional), (PWRT, OST)
Programmable High/ Low-Voltage Detect	Yes	Yes	Yes	Yes
Programmable Brown-out Reset	Yes	Yes	Yes	Yes
Instruction Set	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled	75 Instructions; 83 with Extended Instruction Set Enabled
Packages	28-Pin SPDIP 28-Pin SOIC	28-Pin SPDIP 28-Pin SOIC	40-Pin PDIP 44-Pin QFN 44-Pin TQFP	40-Pin PDIP 44-Pin QFN 44-Pin TQFP
Corresponding Devices with 10-Bit A/D	PIC18F2455	PIC18F2550	PIC18F4455	PIC18F4550

FIGURE 1-1: PIC18F2458/2553 (28-PIN) BLOCK DIAGRAM



Note 1: RE3 is multiplexed with MCLR and is only available when the MCLR Resets are disabled.

2: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O.

3: RB3 is the alternate pin for CCP2 multiplexing.

TABLE 1-2: PIC18F2458/2553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number	Pin Type	Buffer Type	Description
	SPDIP, SOIC			
				PORTA is a bidirectional I/O port.
RA0/AN0	2			
RA0		I/O	TTL	Digital I/O.
AN0		I	Analog	Analog input 0.
RA1/AN1	3			
RA1		I/O	TTL	Digital I/O.
AN1		I	Analog	Analog input 1.
RA2/AN2/VREF-/CVREF	4			
RA2		I/O	TTL	Digital I/O.
AN2		I	Analog	Analog input 2.
VREF-		I	Analog	A/D reference voltage (low) input.
CVREF		O	Analog	Analog comparator reference output.
RA3/AN3/VREF+	5			
RA3		I/O	TTL	Digital I/O.
AN3		I	Analog	Analog input 3.
VREF+		I	Analog	A/D reference voltage (high) input.
RA4/T0CKI/C1OUT/RCV	6			
RA4		I/O	ST	Digital I/O.
T0CKI		I	ST	Timer0 external clock input.
C1OUT		O	—	Comparator 1 output.
RCV		I	TTL	External USB transceiver RCV input.
RA5/AN4/$\overline{SS}$/ HLVDIN/C2OUT	7			
RA5		I/O	TTL	Digital I/O.
AN4		I	Analog	Analog input 4.
$\overline{SS}$		I	TTL	SPI slave select input.
HLVDIN		I	Analog	High/Low-Voltage Detect input.
C2OUT		O	—	Comparator 2 output.
RA6	—	—	—	See the OSC2/CLKO/RA6 pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

TABLE 1-2: PIC18F2458/2553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number: SPDIP, SOIC	Pin Type	Buffer Type	Description
				PORTC is a bidirectional I/O port.
RC0/T1OSO/T13CKI	11			
RC0		I/O	ST	Digital I/O.
T1OSO		O	—	Timer1 oscillator output.
T13CKI		I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2/$\overline{UOE}$	12			
RC1		I/O	ST	Digital I/O.
T1OSI		I	CMOS	Timer1 oscillator input.
CCP2**(2)**		I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
$\overline{UOE}$		—	—	External USB transceiver $\overline{OE}$ output.
RC2/CCP1	13			
RC2		I/O	ST	Digital I/O.
CCP1		I/O	ST	Capture 1 input/Compare 1 output/PWM1 output.
RC4/D-/VM	15			
RC4		I	TTL	Digital input.
D-		I/O	—	USB differential minus line (input/output).
VM		I	TTL	External USB transceiver VM input.
RC5/D+/VP	16			
RC5		I	TTL	Digital input.
D+		I/O	—	USB differential plus line (input/output).
VP		O	TTL	External USB transceiver VP input.
RC6/TX/CK	17			
RC6		I/O	ST	Digital I/O.
TX		O	—	EUSART asynchronous transmit.
CK		I/O	ST	EUSART synchronous clock (see RX/DT).
RC7/RX/DT/SDO	18			
RC7		I/O	ST	Digital I/O.
RX		I	ST	EUSART asynchronous receive.
DT		I/O	ST	EUSART synchronous data (see TX/CK).
SDO		O	—	SPI data out.
RE3	—	—	—	See $\overline{MCLR}$/VPP/RE3 pin.
VUSB	14			Internal USB transceiver power supply.
		O	—	When the internal USB regulator is enabled, VUSB is the regulator output.
		P	—	When the internal USB regulator is disabled, VUSB is the power input for the USB transceiver.
VSS	8, 19	P	—	Ground reference for logic and I/O pins.
VDD	20	P	—	Positive supply for logic and I/O pins.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
MCLR/VPP/RE3	1	18	18			Master Clear (input) or programming voltage (input).
MCLR				I	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
VPP				P		Programming voltage input.
RE3				I	ST	Digital input.
OSC1/CLKI	13	32	30			Oscillator crystal or external clock input.
OSC1				I	Analog	Oscillator crystal input or external clock source input.
CLKI				I	Analog	External clock source input. Always associated with pin function OSC1. (See OSC2/CLKO pin.)
OSC2/CLKO/RA6	14	33	31			Oscillator crystal or clock output.
OSC2				O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode.
CLKO				O	—	In RC mode, OSC2 pin outputs CLKO which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
RA6				I/O	TTL	General purpose I/O pin.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

3: These pins are No Connect unless the ICPRT Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the DEBUG Configuration bit is cleared.

TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTC is a bidirectional I/O port.
RC0/T1OSO/T13CKI	15	34	32			
RC0				I/O	ST	Digital I/O.
T1OSO				O	—	Timer1 oscillator output.
T13CKI				I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2/$\overline{UOE}$	16	35	35			
RC1				I/O	ST	Digital I/O.
T1OSI				I	CMOS	Timer1 oscillator input.
CCP2(2)				I/O	ST	Capture 2 input/Compare 2 output/PWM2 output.
$\overline{UOE}$				O	—	External USB transceiver $\overline{OE}$ output.
RC2/CCP1/P1A	17	36	36			
RC2				I/O	ST	Digital I/O.
CCP1				I/O	ST	Capture 1 input/Compare 1 output/PWM1 output.
P1A				O	TTL	Enhanced CCP1 PWM output, channel A.
RC4/D-/VM	23	42	42			
RC4				I	TTL	Digital input.
D-				I/O	—	USB differential minus line (input/output).
VM				I	TTL	External USB transceiver VM input.
RC5/D+/VP	24	43	43			
RC5				I	TTL	Digital input.
D+				I/O	—	USB differential plus line (input/output).
VP				I	TTL	External USB transceiver VP input.
RC6/TX/CK	25	44	44			
RC6				I/O	ST	Digital I/O.
TX				O	—	EUSART asynchronous transmit.
CK				I/O	ST	EUSART synchronous clock (see RX/DT).
RC7/RX/DT/SDO	26	1	1			
RC7				I/O	ST	Digital I/O.
RX				I	ST	EUSART asynchronous receive.
DT				I/O	ST	EUSART synchronous data (see TX/CK).
SDO				O	—	SPI data out.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

3: These pins are No Connect unless the $\overline{ICPRT}$ Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the $\overline{DEBUG}$ Configuration bit is cleared.

TABLE 1-3: PIC18F4458/4553 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	QFN	TQFP			
						PORTE is a bidirectional I/O port.
RE0/AN5/CK1SPP	8	25	25			
RE0				I/O	ST	Digital I/O.
AN5				I	Analog	Analog input 5.
CK1SPP				O	—	SPP clock 1 output.
RE1/AN6/CK2SPP	9	26	26			
RE1				I/O	ST	Digital I/O.
AN6				I	Analog	Analog input 6.
CK2SPP				O	—	SPP clock 2 output.
RE2/AN7/OESPP	10	27	27			
RE2				I/O	ST	Digital I/O.
AN7				I	Analog	Analog input 7.
OESPP				O	—	SPP output enable output.
RE3	—	—	—	—	—	See $\overline{MCLR}$/VPP/RE3 pin.
VSS	12, 31	6, 30, 31	6, 29	P	—	Ground reference for logic and I/O pins.
VDD	11, 32	7, 8, 28, 29	7, 28	P	—	Positive supply for logic and I/O pins.
VUSB	18	37	37			Internal USB transceiver power supply.
				O	—	When the internal USB regulator is enabled, VUSB is the regulator output.
				P	—	When the internal USB regulator is disabled, VUSB is the power input for the USB transceiver.
NC/ICCK/ICPGC(3)	—	—	12			No Connect or dedicated ICD/ICSP™ port clock.
ICCK				I/O	ST	In-Circuit Debugger clock.
ICPGC				I/O	ST	ICSP programming clock.
NC/ICDT/ICPGD(3)	—	—	13			No Connect or dedicated ICD/ICSP port clock.
ICDT				I/O	ST	In-Circuit Debugger data.
ICPGD				I/O	ST	ICSP programming data.
NC/$\overline{ICRST}$/ICVPP(3)	—	—	33			No Connect or dedicated ICD/ICSP port Reset.
$\overline{ICRST}$				I	—	Master Clear (Reset) input.
ICVPP				P	—	Programming voltage input.
NC/ICPORTS(3)	—	—	34	P	—	No Connect or 28-pin device emulation.
ICPORTS						Enable 28-pin device emulation when connected to VSS.
NC	—	13	—	—	—	No Connect.

Legend: TTL = TTL compatible input; CMOS = CMOS compatible input or output; ST = Schmitt Trigger input with CMOS levels; I = Input; O = Output; P = Power

Note 1: Alternate assignment for CCP2 when CCP2MX Configuration bit is cleared.

2: Default assignment for CCP2 when CCP2MX Configuration bit is set.

3: These pins are No Connect unless the $\overline{ICPRT}$ Configuration bit is set. For NC/ICPORTS, the pin is No Connect unless ICPRT is set and the $\overline{DEBUG}$ Configuration bit is cleared.

The analog reference voltage is software selectable to either the device's positive and negative supply voltage (V_{DD} and V_{SS}), or the voltage level on the RA3/AN3/V_{REF+} and RA2/AN2/V_{REF-}/CV_{REF} pins.

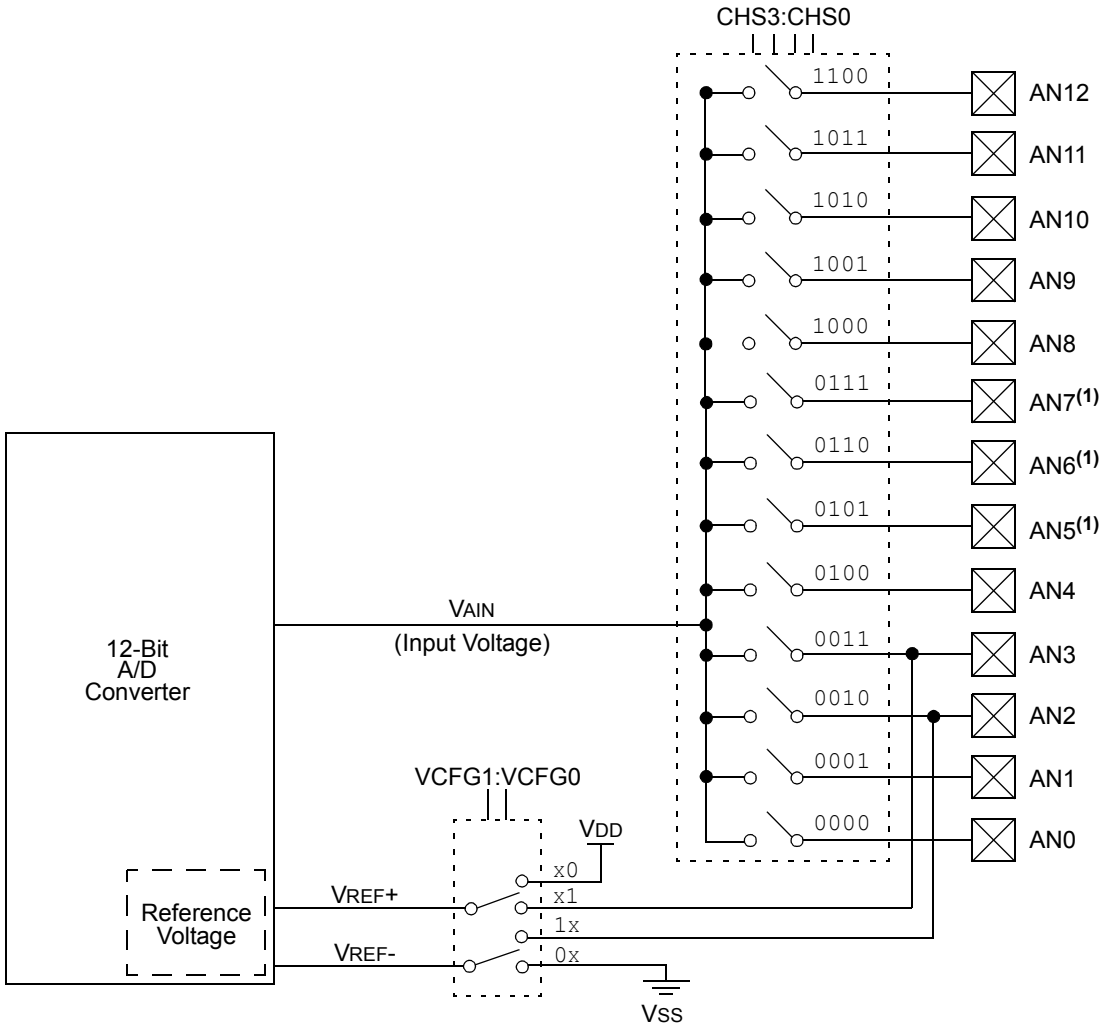
The A/D Converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

The output of the sample and hold is the input into the Converter, which generates the result via successive approximation.

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off and any conversion in progress is aborted.

Each port pin associated with the A/D Converter can be configured as an analog input or as a digital I/O. The ADRESH and ADRESL registers contain the result of the A/D conversion. When the A/D conversion is complete, the result is loaded into the ADRESH:ADRESL register pair, the GO/$\overline{\text{DONE}}$ bit (ADCON0 register) is cleared and the A/D Interrupt Flag bit, ADIF, is set. The block diagram of the A/D module is shown in Figure 2-1.

FIGURE 2-1: A/D BLOCK DIAGRAM



Note 1: Channels AN5 through AN7 are not available on 28-pin devices.

The value in the ADRESH:ADRESL registers is unknown following Power-on and Brown-out Resets, and is not affected by any other Reset.

After the A/D module has been configured as desired, the selected channel must be acquired before the conversion is started. The analog input channels must have their corresponding TRIS bits selected as an input. To determine acquisition time, see **Section 2.1 "A/D Acquisition Requirements"**. After this acquisition time has elapsed, the A/D conversion can be started. An acquisition time can be programmed to occur between setting the GO/$\overline{\text{DONE}}$ bit and the actual start of the conversion.

The following steps should be followed to perform an A/D conversion:

1. Configure the A/D module:
   - Configure analog pins, voltage reference and digital I/O (ADCON1)
   - Select A/D input channel (ADCON0)
   - Select A/D acquisition time (ADCON2)
   - Select A/D conversion clock (ADCON2)
   - Turn on A/D module (ADCON0)
2. Configure A/D interrupt (if desired):
   - Clear ADIF bit
   - Set ADIE bit
   - Set GIE bit
3. Wait the required acquisition time (if required).
4. Start conversion:
   - Set GO/$\overline{\text{DONE}}$ bit (ADCON0 register)
5. Wait for A/D conversion to complete, by either:
   - Polling for the GO/$\overline{\text{DONE}}$ bit to be cleared

   OR
   - Waiting for the A/D interrupt
6. Read A/D Result registers (ADRESH:ADRESL); clear bit ADIF, if required.
7. For next conversion, go to step 1 or step 2, as required. The A/D conversion time per bit is defined as TAD. A minimum wait of 2 TAD is required before the next acquisition starts.

FIGURE 2-2: A/D TRANSFER FUNCTION

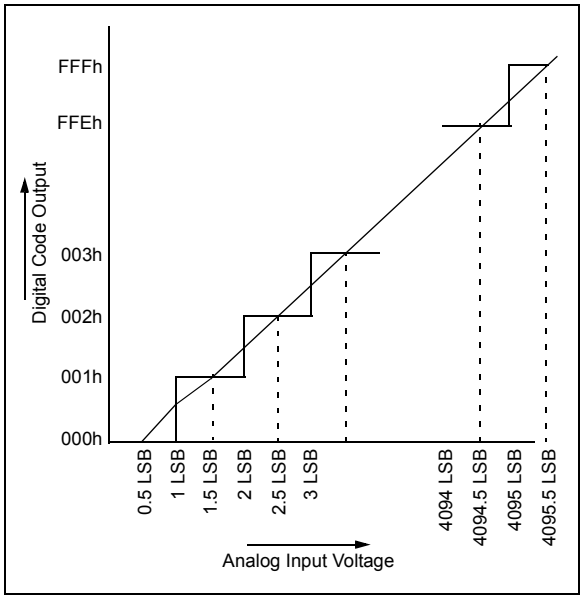
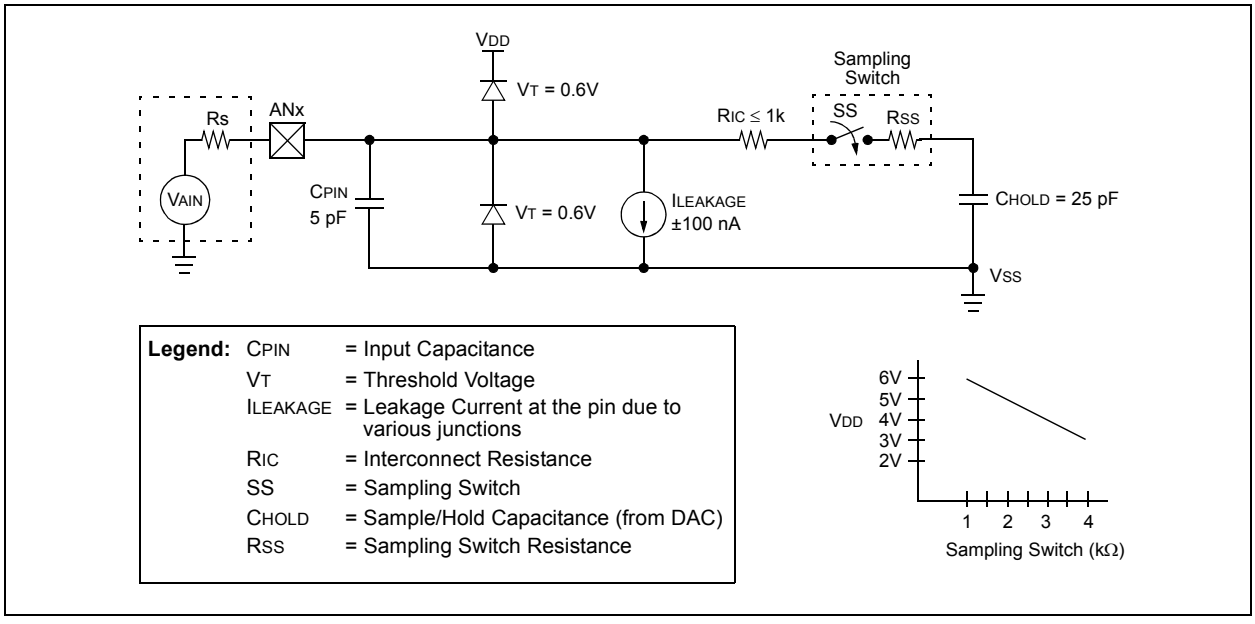


FIGURE 2-3: ANALOG INPUT MODEL



2.4 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ADCS2:ADCS0 bits in ADCON2 should be updated in accordance with the clock source to be used. The ACQT2:ACQT0 bits do not need to be adjusted as the ADCS2:ADCS0 bits adjust the T_{AD} time for the new clock speed. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D F_{RC} clock to be selected. If bits ACQT2:ACQT0 are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

2.5 Configuring Analog Port Pins

The ADCON1, TRISA, TRISB and TRISE registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (V_{OH} or V_{OL}) will be converted.

The A/D operation is independent of the state of the CHS3:CHS0 bits and the TRIS bits.

Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog conversion on pins configured as digital pins can be performed. The voltage on the pin will be accurately converted.

2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.

3: The PBADEN bit in Configuration Register 3H configures PORTB pins to reset as analog or digital pins by controlling how the PCFG3:PCFG0 bits in ADCON1 are reset.

2.6 A/D Conversions

Figure 2-4 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT2:ACQT0 bits are cleared. A conversion is started after the following instruction to allow entry into Sleep mode before the conversion begins.

Figure 2-5 shows the operation of the A/D Converter after the GO/$\overline{\text{DONE}}$ bit has been set and the ACQT2:ACQT0 bits are set to '010', and selecting a 4 TAD acquisition time before the conversion starts.

Clearing the GO/$\overline{\text{DONE}}$ bit during a conversion will abort the current conversion. The A/D Result register pair will NOT be updated with the partially completed A/D conversion sample. This means the ADRESH:ADRESL registers will continue to contain the value of the last completed conversion (or the last value written to the ADRESH:ADRESL registers).

After the A/D conversion is completed or aborted, a 2 TCY wait is required before the next acquisition can be started. After this wait, acquisition on the selected channel is automatically started.

Note: The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D. Code should wait at least 2 μs after enabling the A/D before beginning an acquisition and conversion cycle.

2.7 Discharge

The discharge phase is used to initialize the value of the holding capacitor. The array is discharged before every sample. This feature helps to optimize the unity gain amplifier, as the circuit always needs to charge the capacitor array, rather than charge/discharge based on previous measure values.

FIGURE 2-4: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 000, TACQ = 0)

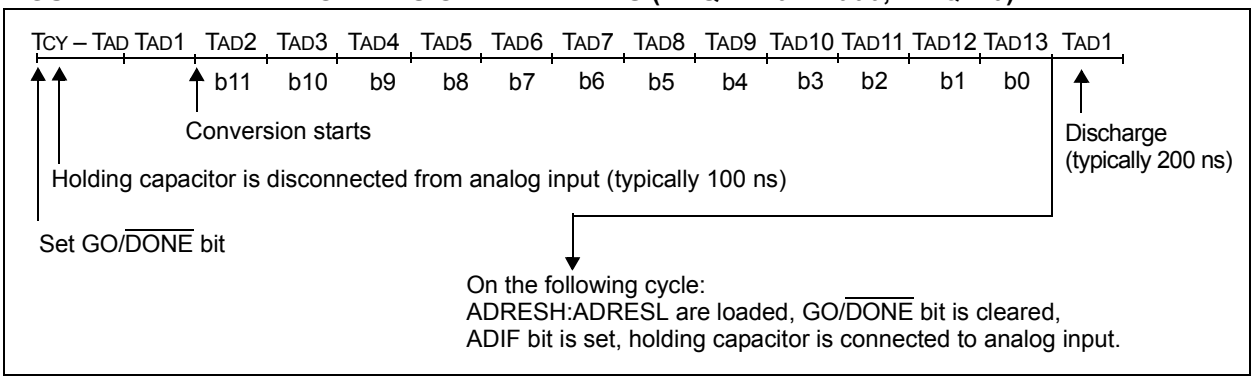
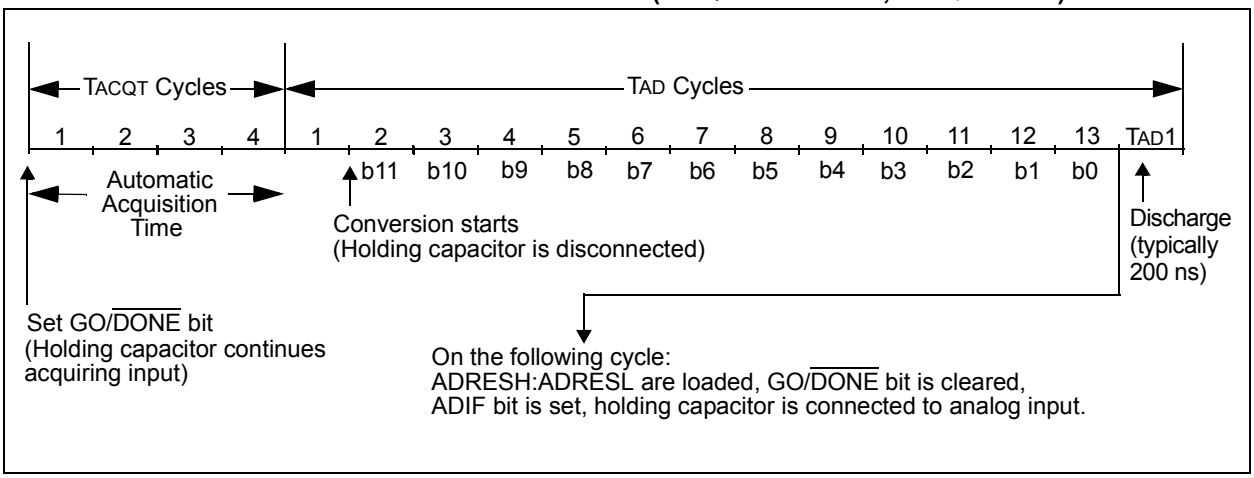


FIGURE 2-5: A/D CONVERSION TAD CYCLES (ACQT<2:0> = 010, TACQ = 4 TAD)



2.8 Use of the CCP2 Trigger

An A/D conversion can be started by the Special Event Trigger of the CCP2 module. This requires that the CCP2M3:CCP2M0 bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/DONE bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (firmware must move ADRESH:ADRESL to the desired location). The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user, or an appropriate TACQ time selected before the Special Event Trigger sets the GO/DONE bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

TABLE 2-2: REGISTERS ASSOCIATED WITH A/D OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on Page:
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	(4)
PIR1	SPPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	(4)
PIE1	SPPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	(4)
IPR1	SPPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	(4)
PIR2	OSCFIF	CMIF	USBIF	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	(4)
PIE2	OSCFIE	CMIE	USBIE	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	(4)
IPR2	OSCFIP	CMIP	USBIP	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	(4)
ADRESH	A/D Result Register High Byte								(4)
ADRESL	A/D Result Register Low Byte								(4)
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/DONE	ADON	21
ADCON1	—	—	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	22
ADCON2	ADFM	—	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	23
PORTA	—	RA6(2)	RA5	RA4	RA3	RA2	RA1	RA0	(4)
TRISA	—	TRISA6(2)	PORTA Data Direction Control Register						(4)
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	(4)
TRISB	PORTB Data Direction Control Register								(4)
LATB	PORTB Data Latch Register (Read and Write to Data Latch)								(4)
PORTE(1)	RDPU	—	—	—	RE3(3)	RE2(1)	RE1(1)	RE0(1)	(4)
TRISE(1)	—	—	—	—	—	TRISE2	TRISE1	TRISE0	(4)
LATE(1)	—	—	—	—	—	PORTE Data Latch Register			(4)

Legend: — = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

Note 1: These registers and/or bits are not implemented on 28-pin devices and are read as '0'.

2: RA6 and its associated latch and data direction bits are enabled as I/O pins based on oscillator configuration; otherwise, they are read as '0'.

3: RE3 port bit is available only as an input pin when the MCLRE Configuration bit is '0'.

4: For these Reset values, see the *"PIC18F2455/2550/4455/4550 Data Sheet"*.

3.0 SPECIAL FEATURES OF THE CPU

Note: For additional details on the Configuration bits, refer to the *"PIC18F2455/2550/4455/4550 Data Sheet"*, **Section 25.1 "Configuration Bits"**. Device ID information presented in this section is for PIC18F2458/2553/4458/4553 only.

PIC18F2458/2553/4458/4553 devices include several features intended to maximize reliability and minimize cost through elimination of external components. These include:

- Device ID Registers

3.1 Device ID Registers

The Device ID registers are "read-only" registers. They identify the device type and revision to device programmers, and can be read by firmware using table reads.

TABLE 3-1: DEVICE IDs

File Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default/ Unprogrammed Value
3FFFFEh	DEVID1	DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0	xxxx xxxx(1)
3FFFFFh	DEVID2	DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3	xxxx xxxx(1)

Legend: x = unknown, u = unchanged

Note 1: See Register 3-1 and Register 3-2 for DEVID values. DEVID registers are read-only and cannot be programmed by the user.

REGISTER 3-1: DEVID1: DEVICE ID REGISTER 1 FOR PIC18F2458/2553/4458/4553 DEVICES

R	R	R	R	R	R	R	R
DEV2	DEV1	DEV0	REV4	REV3	REV2	REV1	REV0
bit 7							bit 0

Legend:		
R = Read-only bit	P = Programmable bit	U = Unimplemented bit, read as ‘0’
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-5 **DEV2:DEV0:** Device ID bits
See Register 3-2 for a complete listing.

bit 4-0 **REV3:REV0:** Revision ID bits
These bits are used to indicate the device revision.

REGISTER 3-2: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F2458/2553/4458/4553 DEVICES

R	R	R	R	R	R	R	R
DEV10	DEV9	DEV8	DEV7	DEV6	DEV5	DEV4	DEV3
bit 7							bit 0

Legend:		
R = Read-only bit	P = Programmable bit	U = Unimplemented bit, read as ‘0’
-n = Value when device is unprogrammed		u = Unchanged from programmed state

bit 7-0 **DEV10:DEV3:** Device ID bits

DEV10:DEV3 (DEVID2<7:0>)	**DEV2:DEV0 (DEVID1<7:5>)**	**Device**
0010 1010	011	PIC18F2458
0010 1010	010	PIC18F2553
0010 1010	001	PIC18F4458
0010 1010	000	PIC18F4553

4.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD} and $\overline{MCLR}$) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Total power dissipation **(Note 1)** 1.0W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by all ports ..... 200 mA
Maximum current sourced by all ports ..... 200 mA

Note 1: Power dissipation is calculated as follows:
$P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}$/V_{PP}/RE3 pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$/V_{PP}/RE3 pin, rather than pulling this pin directly to V_{SS}.

† **NOTICE:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

FIGURE 4-1: PIC18F2458/2553/4458/4553 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)

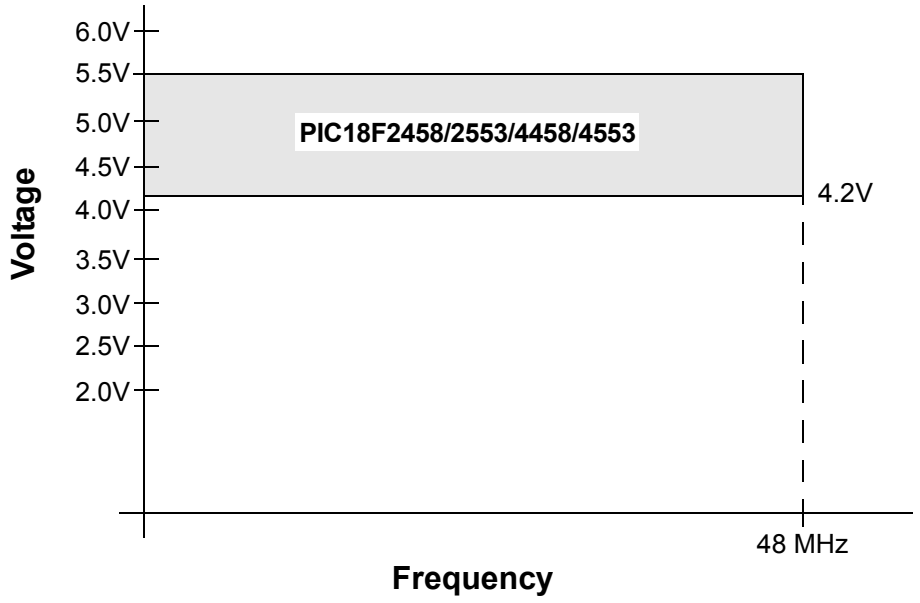
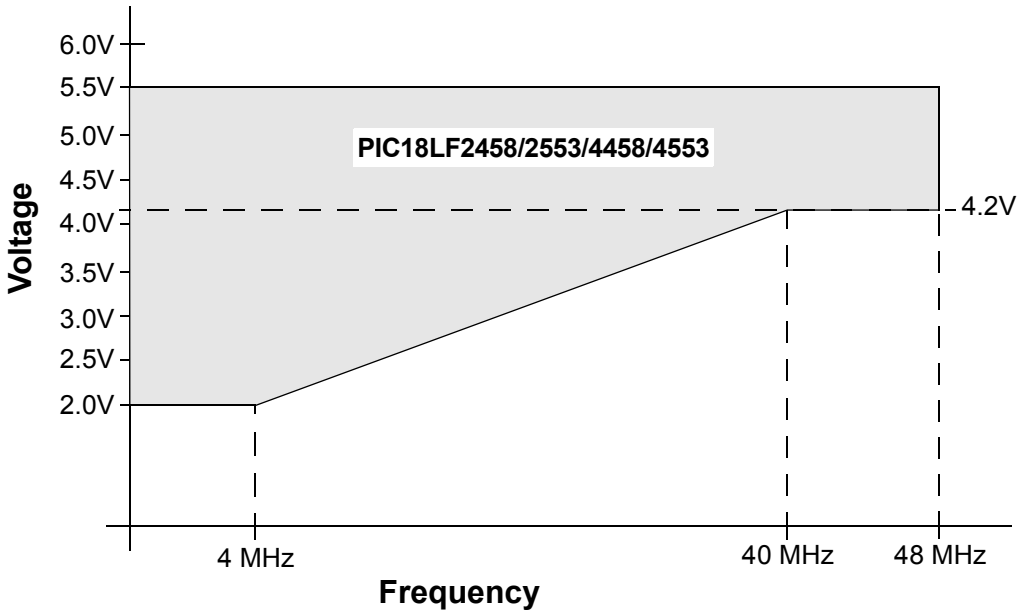


FIGURE 4-2: PIC18LF2458/2553/4458/4553 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)



For 2.0V ≤ V_{DD} < 4.2V: F_{MAX} = (16.36 MHz/V) ($V_{DDAPPMIN}$ – 2.0V) + 4 MHz
For 4.2V ≤ V_{DD}: F_{MAX} = 48 MHz

Note: $V_{DDAPPMIN}$ is the minimum voltage of the PIC® device in the application.

5.0 PACKAGING INFORMATION

For packaging information, see the *"PIC18F2455/2550/4455/4550 Data Sheet"* (DS39632).

APPENDIX A: REVISION HISTORY

Revision A (May 2007)

Original data sheet for the PIC18F2458/2553/4458/4553 devices.

Revision B (June 2007)

Changes to Figure 4-2: PIC18LF2458/2553/4458/4553 Voltage-Frequency Graph (Industrial).

Revision C (October 2009)

Removed “Preliminary” marking.

APPENDIX B: DEVICE DIFFERENCES

The differences between the devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Features	PIC18F2458	PIC18F2553	PIC18F4458	PIC18F4553
Program Memory (Bytes)	24576	32768	24576	32768
Program Memory (Instructions)	12288	16384	12288	16384
Interrupt Sources	19	19	20	20
I/O Ports	Ports A, B, C, (E)	Ports A, B, C, (E)	Ports A, B, C, D, E	Ports A, B, C, D, E
Capture/Compare/PWM Modules	2	2	1	1
Enhanced Capture/Compare/ PWM Modules	0	0	1	1
Parallel Communications (SPP)	No	No	Yes	Yes
12-Bit Analog-to-Digital Module	10 Input Channels	10 Input Channels	13 Input Channels	13 Input Channels
Packages	28-Pin SPDIP 28-Pin SOIC	28-Pin SPDIP 28-Pin SOIC	40-Pin PDIP 44-Pin TQFP 44-Pin QFN	40-Pin PDIP 44-Pin TQFP 44-Pin QFN

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com, click on Customer Change Notification and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support
- Development Systems Information Line

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://support.microchip.com

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	X	/XX	XXX
Device	Temperature Range	Package	Pattern

Device	PIC18F2458/2553(1), PIC18F4458/4553(1), PIC18F2458/2553T(2), PIC18F4458/4553T(2); VDD range 4.2V to 5.5V PIC18LF2458/2553(1), PIC18LF4458/4553(1), PIC18LF2458/2553T(2), PIC18LF4458/4553T(2); VDD range 2.0V to 5.5V	
Temperature Range	I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)	
Package	PT = TQFP (Thin Quad Flatpack) SO = SOIC SP = Skinny PDIP P = PDIP ML = QFN	
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)	

Examples:

a) PIC18LF4553-I/P 301 = Industrial temp., PDIP package, Extended VDD limits, QTP pattern #301.

b) PIC18LF2458-I/SO = Industrial temp., SOIC package, Extended VDD limits.

c) PIC18F4458-I/P = Industrial temp., PDIP package, normal VDD limits.

Note 1: F = Standard Voltage Range
LF = Wide Voltage Range

2: T = In tape and reel TQFP packages only.